

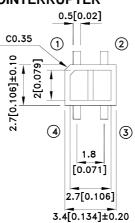
SUBMINIATURE, HIGH SENSITIVITY PHOTOINTERRUPTER

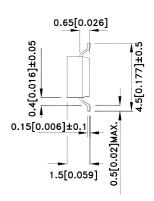
*Features

- · Compact and thin.
- Visible light cut-off type.
- High sensitivity.
- Package:1000pcs/Reel.
- Moisture sensitivity level : level 4.
- RoHS Compliant.

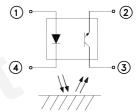
*Applications

- Cassette tape recorders, VCRs.
- Floppy disk drives.
- Various microcomputerized control equipment.





- 1) Anode
- 2 Emitter
- 3 Collector
- 4 Cathode



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25 (0.01")$ unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

*Absolute Maximum Ratings

	Parameter	Symbol	Rating	Unit
	Forward current		50	mA
Input	Reverse voltage	V _R	6	V
	Power dissipation	P _D	75	mW
	Peak Forward Current (Pulse Width ≤100uS, Duty Cycle =1%)	I _{FP}	1	A
Output	Collector-emitter voltage	V _{CEO}	35	V
	Emitter-collector voltage	V _{ECO}	6	V
	Collector current	Ic	20	mA
	Collector power dissipation	Pc	75	mW
Operating to	emperature	Topr	-25~+85	°C
Storage temperature		Tstg	-40~+100	°C
soldering temperature (1/16 inch from body for 5 seconds)		Tsol	260	°C

1. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.





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■Electro-optical Characteristics

	Parameter		Symbol	Conditions	Min.	TYP.	Max.	Unit
Input	Forward Voltage		V _F	I _F =20mA	1.0	1.2	1.5	V
	Reverse Current		I _R	V _R =6V	-	-	10	μΑ
	Peak Wavelength		λР	I _F =20mA	-	940	-	nm
Output	Collector Dark C	urrent	I _{CEO}	V _{CE} =20V	-	10 ⁻⁹	10 ⁻⁷	Α
	*1 Collector Current		I _C	V _{CE} =2V I _F =4mA	10	-	400	μА
Transfer charact-	*2 Leak Current		I _{LEAK}	V _{CE} =2V I _F =4mA	-	-	0.1	μΑ
eristics	Response time	Rise time	tr	V _{CE} =2V	-	20	100	μsec
		Fall time	tf	I_C =100μA R_L =1KΩ,d=1mm	-	20	100	μsec

^{*1} The condition and arrangement of the reflective object are shown below.

■ Classification table of radiant flux

BIN CODE	E	F	G	
Ic (μA)	10~120	100~250	200~400	

Test Condition and Al evaporation Arrangement for Collector Current

Fig. 1 Forward Current vs. Forward Voltage

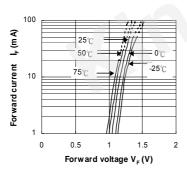


Fig. 3 Collector Current vs.
Collector—emitter Voltage

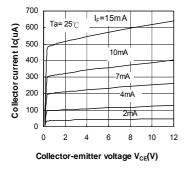


Fig. 2 Collector Current vs. Forward Current

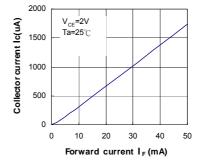
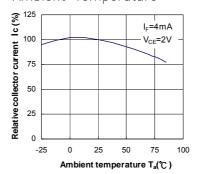


Fig. 4 Relative Collector Current vs. Ambient Temperature



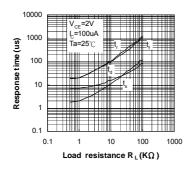
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^{*2} Without reflective object.

^{*3} Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Fig. 5 Response Time vs. Load Resistance

Test Circuit for Response Time



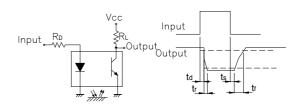
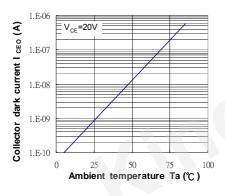


Fig. 6 Collector Dark Current vs. Fig. 7 Relative Collector Current vs.

Ambient Temperature Distance between Sensor and
Al Evaporation Glass



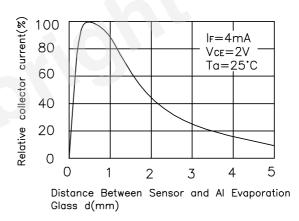
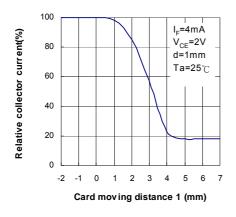
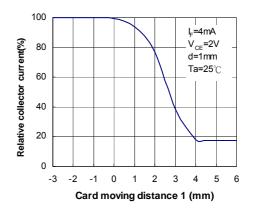


Fig. 8 Relative Collector Current vs. Fig. 9 Relative Collector Current vs. Card Moving Distance (1) Card Moving Distance (2)





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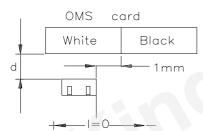
Test Condition for Distance & Detecting PositionCharacteristics

Correpond to Fig. 7



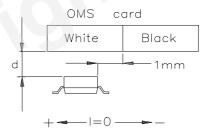
Correpond to Fig. 8
Test condition

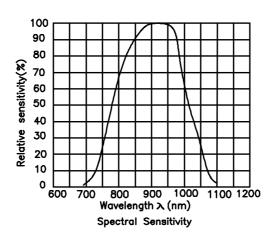
 $I_F=4mA$ $V_{CE}=2V$ d=1mm



Correpond to Fig. 9
Test condition

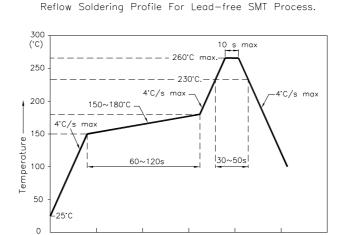
 $I_F=4mA$ $V_{CE}=2V$ d=1mm





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NOTES:

50

100

Time -

0

1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.

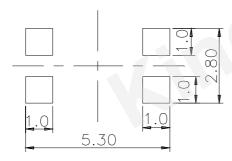
200

250

- 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

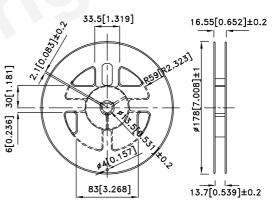
150

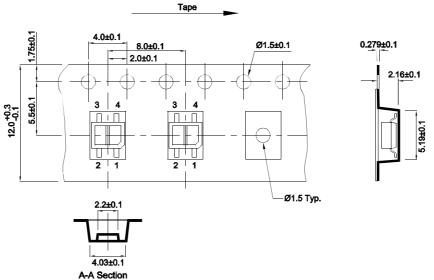
Recommended Soldering Pattern (Units: mm; Tolerance: ±0.1)



Tape Specifications (Units : mm)

Reel Dimension

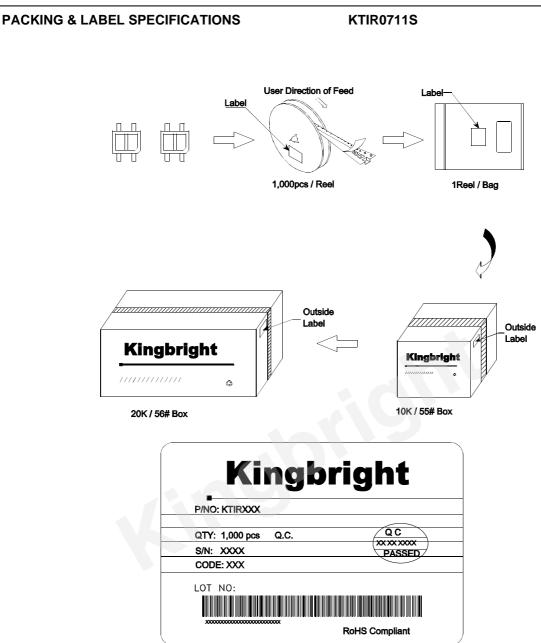




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